

### AP9575GH-HF-VB Datasheet

## P-Channel 60-V (D-S) MOSFET

PRODUCT SUMMARY					
V <sub>DS</sub> (V)	<b>R<sub>DS(on)</sub> (</b> Ω <b>)</b>	I <sub>D</sub> (A)	Q <sub>g</sub> (Typ)		
- 60	0.061 at V <sub>GS</sub> = - 10 V	- 30	10		
- 60	0.072 at V <sub>GS</sub> = - 4.5 V	- 25	10		

#### FEATURES

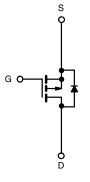
- Trench Power MOSFET
- 100 % UIS Tested

#### **APPLICATIONS**

Load Switch







P-Channel MOSFET

Parameter	Symbol	Limit	Unit		
Gate-Source Voltage	V <sub>GS</sub>	± 20	V		
Continuous Drain Current ( $T_1 = 175 ^{\circ}C$ )	T <sub>C</sub> = 25 °C	1_	- 30		
Continuous Drain Current $(1) = 175$ C)	T <sub>C</sub> = 100 °C	ID –	- 25		
Pulsed Drain Current	I <sub>DM</sub>	- 30	А		
Continuing Source Current (Diode Conduction)	۱ <sub>S</sub>	- 20			
Avalanche Current	I <sub>AS</sub>	- 20	1		
Single Pulse Avalanche Energy	L = 0.1 mH	E <sub>AS</sub>	7.2	mJ	
Maximum Dawar Dissinction	T <sub>C</sub> = 25 °C	В	34 <sup>a</sup>	w	
Maximum Power Dissipation	T <sub>A</sub> = 25 °C	P <sub>D</sub>	4 <sup>b</sup>	~ ~ ~	
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to 175	°C	

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
hundling to Anching b	t ≤ 10 sec	D	20	25	°C/W	
Junction-to-Ambient <sup>D</sup>	Steady State	R <sub>thJA</sub>	62	75		
Junction-to-Case		R <sub>thJC</sub>	5	6		

Notes:

a. See SOA curve for voltage derating.

b. Surface Mounted on 1" x 1" FR-4 boad.

<b>SPECIFICATIONS</b> $T_J = 25 \text{ °C}$ , unless otherwise noted							
Parameter	Symbol	Test Conditions	Min	Typ <sup>a</sup>	Мах	Unit	
Static							
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	$V_{GS} = 0 \text{ V}, \text{ I}_{D} = -250 \mu\text{A}$				v	
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}$ , $I_D = -250 \ \mu A$	- 1.0	- 2.0	- 3.0	v	
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA	
	I <sub>DSS</sub>	$V_{DS} = -60 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$			- 1		
Zero Gate Voltage Drain Current		$V_{DS}$ = - 60 V, $V_{GS}$ = 0 V, $T_{J}$ = 125 °C			- 50	μΑ	
		$V_{DS}$ = - 60 V, $V_{GS}$ = 0 V, $T_{J}$ = 175 °C			- 150		
On-State Drain Current <sup>b</sup>	I <sub>D(on)</sub>	V <sub>DS</sub> = - 5 V, V <sub>GS</sub> = - 10 V	- 10			А	
		V <sub>GS</sub> = - 10 V, I <sub>D</sub> = - 5 A		0.061			
	-	$V_{GS}$ = - 10 V, I <sub>D</sub> = - 5 A, T <sub>J</sub> = 125 °C		0.100		Ω	
Drain-Source On-State Resistance <sup>b</sup>	<sup>r</sup> DS(on)	$V_{GS}$ = - 10 V, I <sub>D</sub> = - 5 A, T <sub>J</sub> = 175 °C		0.150			
		V <sub>GS</sub> = - 4.5 V, I <sub>D</sub> = - 2 A		0.072			
Forward Transconductanceb	9 <sub>fs</sub>	V <sub>DS</sub> = - 15 V, I <sub>D</sub> = - 5 A		8		S	
Dynamic	ļ						
Input Capacitance	C <sub>iss</sub>			1000		pF	
Output Capacitance	C <sub>oss</sub>	$V_{DS}$ = - 25 V, $V_{GS}$ = 0 V, f = 1 MHz		120			
Reverse Transfer Capacitance	C <sub>rss</sub>			100			
Total Gate Charge	Qg			10		nC	
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS} = -30$ V, $V_{GS} = -10$ V, $I_{D} = -8.4$ A		2.1			
Gate-Drain Charge	Q <sub>gd</sub>			3.2		1	
Gate Resistance	R <sub>g</sub>	f = 1 MHz		8.0		Ω	
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			6			
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD} = -30 \text{ V}, \text{ R}_{L} = 3.57 \Omega$		15		ns	
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>	$\text{I}_{\text{D}}\cong$ - 8.4 A, $\text{V}_{\text{GEN}}$ = - 10 V, $\text{R}_{\text{G}}$ = 2.5 $\Omega$		16			
Fall Time <sup>c</sup>	t <sub>f</sub>			8		1	
Source-Drain Diode Ratings and Cha	racteristics	(T <sub>C</sub> = 25 °C) <sup>b</sup>					
Pulsed Current	I <sub>SM</sub>				- 30	А	
Forward Voltage <sup>b</sup>	V <sub>SD</sub>	$I_{F} = -2 \text{ A}, V_{GS} = 0 \text{ V}$		- 0.9	- 1.3	V	
Reverse Recovery Time	t <sub>rr</sub>			50		ns	
Reverse Recovery Time	Q <sub>rr</sub>	I <sub>F</sub> = - 8 A, di/dt = 100 A/μs		80		nC	

Notes:

a. Guaranteed by design, not subject to production testing.

b. Pulse test; pulse width  $\leq$  300  $\mu s,$  duty cycle  $\leq$  2 %.

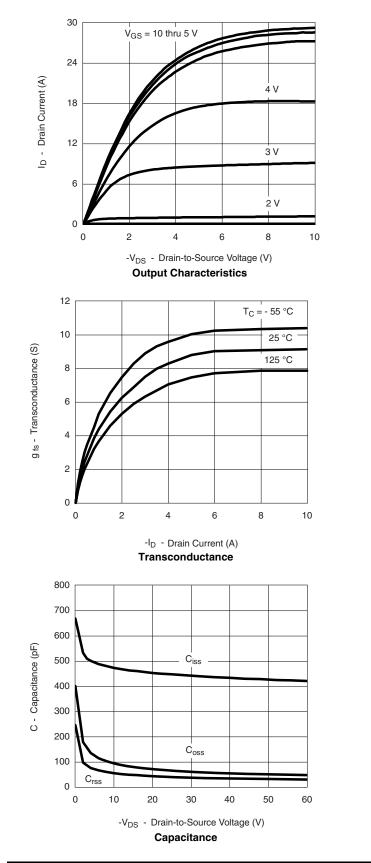
c. Independent of operating temperature.

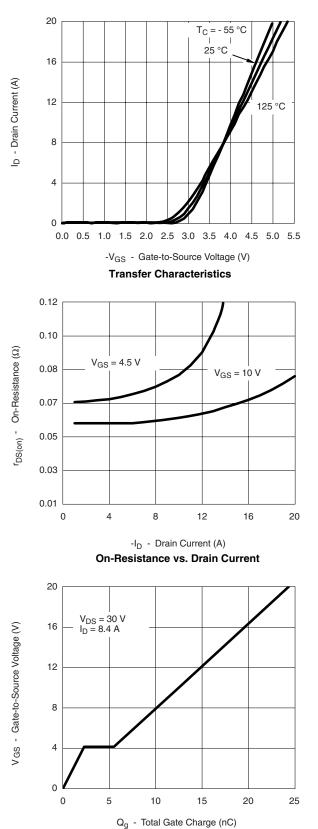
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

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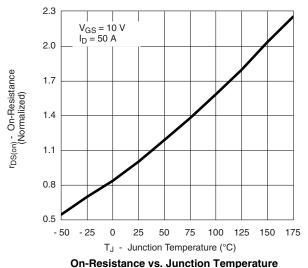


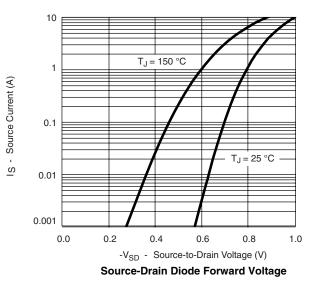




Gate Charge

#### TYPICAL CHARACTERISTICS 25 °C unless noted



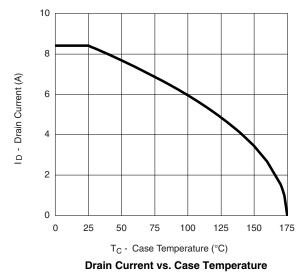


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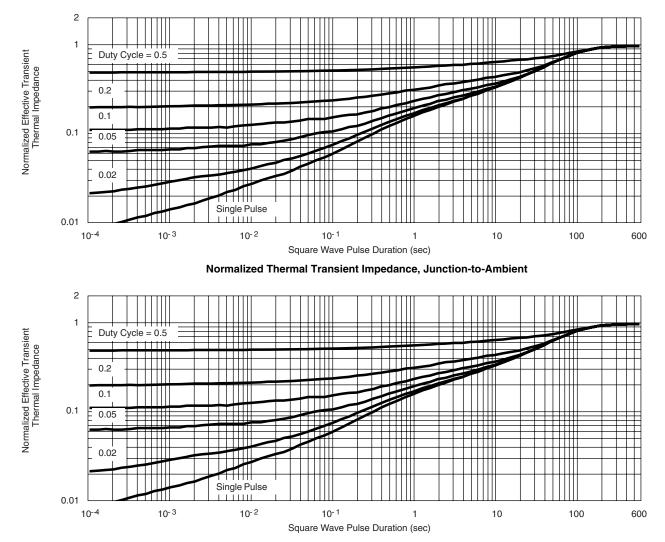
100 10 µs 10\*Limited by <u></u> 100 μs I D - Drain Current (A) TL ms 1 10 ms 100 ms, DC 0.1 T<sub>C</sub> = 25 °C Single Pulse 0.01 Ħ 0.001 0.1 1 10 100 -V\_{DS} - Drain-to-Source Voltage (V)  $^{*}V_{GS}$  > minimum V\_{GS} at which  $r_{DS(\text{on})}$  is specified Safe Operating Area

#### THERMAL RATINGS





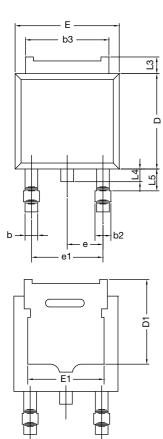
#### THERMAL RATINGS

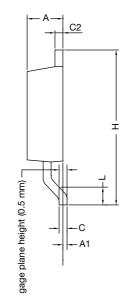


Normalized Thermal Transient Impedance, Junction-to-Case









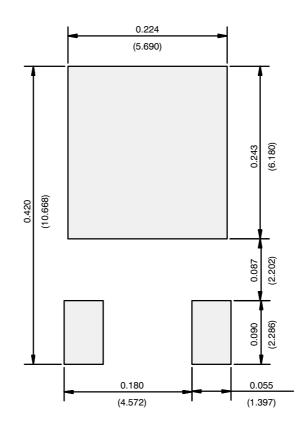
	MILLIN	IETERS	INCHES		
DIM.	MIN.	MAX.	MIN.	MAX.	
А	2.18	2.38	0.086	0.094	
A1	-	0.127	-	0.005	
b	0.64	0.88	0.025	0.035	
b2	0.76	1.14	0.030	0.045	
b3	4.95	5.46	0.195	0.215	
С	0.46	0.61	0.018	0.024	
C2	0.46	0.89	0.018	0.035	
D	5.97	6.22	0.235	0.245	
D1	5.21	-	0.205	-	
Е	6.35	6.73	0.250	0.265	
E1	4.32	-	0.170	-	
Н	9.40	10.41	0.370	0.410	
е	2.28	BSC	0.090 BSC		
e1	4.56	BSC	0.180 BSC		
L	1.40	1.78	0.055	0.070	
L3	0.89	1.27	0.035	0.050	
L4	-	1.02	-	0.040	
L5	1.14	1.52	0.045	0.060	
ECN: X12-( DWG: 5347	)247-Rev. M,	24-Dec-12			

Note

• Dimension L3 is for reference only.



#### **RECOMMENDED MINIMUM PADS FOR DPAK (TO-252)**



Recommended Minimum Pads Dimensions in Inches/(mm)



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